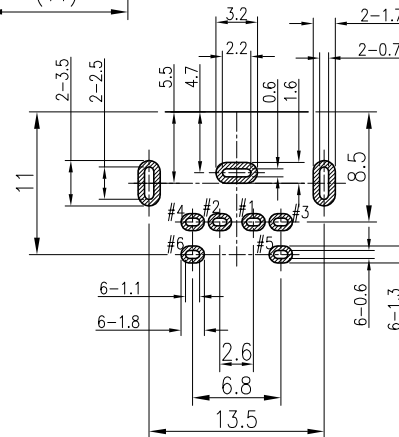
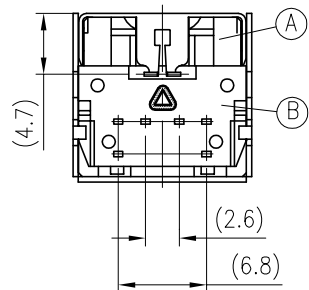
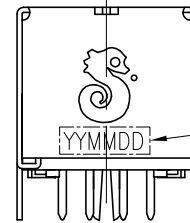
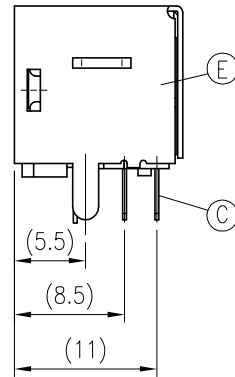
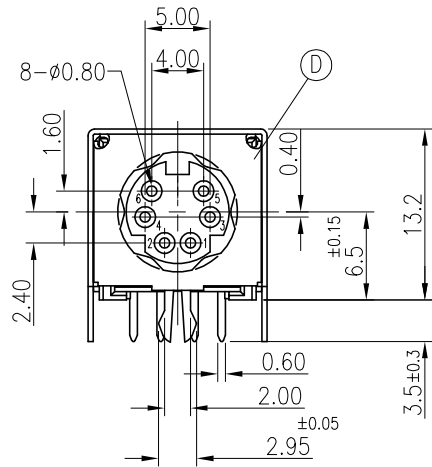
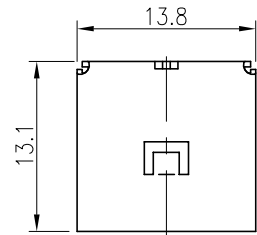


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	ECN NO.: C202203-R04	Zhongjian	2022.05.10



RECOMMENDED PCB LAYOUT (SOLDER SIDE)
BOTTOM VIEW (TOLRANCE: ±0.05)

- CURRENT CARRYING CAPACITY:
1-1. AC:100V 1A MAX.
1-2. DC:12V 3A MAX.
- CONTACT RESISTANCE:
2-1. INITIAL, BEFORE LIFE CYCLE TEST.
PIN TO CONTACT: 30mΩ MAX.
PLUG SHIELD TO CONNECTOR: 50mΩ MAX.
2-2. AFTER LIFE CYCLE TEST.
PIN TO CONTACT: 80mΩ MAX.
PLUG SHIELD TO CONNECTOR: 100mΩ MAX.
- INSULATION RESISTANCE:
BETWEEN ANY ADJACENT OPEN CONTACTS SHALL NOT BE LESS THAN 100MΩ AT 250V DC INSULATION RESISTANCE TEST.
- DIELECTRIC STRENGTH:
A POTENTIAL OF 250V AC R.M.S. 50/60HZ SHALL BE APPLIED BETWEEN ANY OPEN CONTACTS FOR ONE MINUTE WITHOUT BREAKDOWN.
- INSERTION FORCE: 4.5Kg MAX.
- WITHDRAWAL FORCE: 0.8Kg - 3.5Kg.
- SINGLE CONTACT MAINTENANCE FORCE: 30g MIN.
BETWEEN EACH CONTACT AND MATCHING PIN (0.6 ±0.03 DIA).
- LIFE CYCLE TEST:
CONNECTOR SHALL BE SUBJECT TO 5,000 CYCLES AT 10 TO 20 CYCLES PER MINUTE WITH NO ELECTRICAL LOAD.
- MARKING: MARK "S" ON REAR OF CONNECTOR.
- TO CONFORM TO THE SINGATRON HSF SPEC.
- GREEN PRODUCT IDENTIFICATION MARK ON JACK:
- GREEN PRODUCT IDENTIFICATION LABEL ON PACKAGING: **G.P. PASS**
- FOR REFLOW SOLDERING LEAD-FREE PROCESS.
- PRINTED DATE CODE "YYMMDD" ON TOP OF CONNECTOR.
DATE CODE: YYMMDD

DD: DAY
MM: MONTH
YY: YEAR

E	SHIELDING B	1	SPCC 0.4t	TIN PLATING (LF)
D	SHIELDING A	1	COPPER ALLOY 0.3t	TIN PLATING (LF)
C	CONTACT	6	COPPER ALLOY 0.3t	SILVER PLATING
B	COVER	1	THERMOPLASTIC	BLACK COLOR
A	BODY	1	THERMOPLASTIC	BLACK COLOR
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

DECIMALS: X : ±0.5
X.X : ±0.3
X.XX : ±0.2

ANGLES: X : ±2°
X.X : ±1°

TITLE	MINIATURE DIN CONNECTOR(WITH GROUND FINGER)		
DWN	Zhongjian-Wu	PART NO. 2MJ-1514A110	
CHKD	Stone-Zhu	SCALE 1:1	UNIT: mm
APVD	Jim-Deng	SIZE: A3	SHEET: 10F1 REV: A

CUSTOMER COPY